

ABSTRACT

A method of making an RFID device which includes the steps of (a) applying a UV curable adhesive having electrically conductive particles therein to a pair of laterally displaced landing sites of antenna formed on a UV penetrable web in a manner such that the particles remain spatially positioned from one another, (b) bringing a pair die pads of a die into sufficient electrical contact with the landing sites to effect a Z axis conductivity through the particles between a respective die pad and landing site pad pair while precluding X-Y conductivity between the landing site pads, and (c) UV irradiating of the adhesive through and/or about the web in a manner to cure the adhesive join the die to the antenna. An RFID device is also provided by the process.